

# PRODUCT SPECIFICATION

**Model No : CSSC-NPLSB54XX-YSX**

Descriptions:	
• Product Type	: Chip LED
• Package Size	: 3.2x1.6x1.85mm
• Emitting Color	: Blue



CUSTOMER APPROVED SIGNATURES	APPROVED BY	CHECKED BY	PREPARED BY
	<div>2022.03.18</div> <div>Leon</div> <div>All right reserved</div>	<div>2022.03.18</div> <div>ZXY</div> <div>All right reserved</div>	<div>2022.03.18</div> <div>ZHH</div> <div>All right reserved</div>

**OPTO PLUS TECHNOLOGIES CO.,LTD**

Address : No.696,Yangming North Rd,ShaoXing

City,ZheJiang Province,P.R.China,312000

Tel : 86-575-88623888

Fax : 86-575-88623112

<http://www.csbright.com>

## ■ Absolute Maximum Rating Polarity–

(Ta=25°C)

Parameter	Symbol	Value	Unit
Forward current	I <sub>F</sub>	30	mA
Pulse Forward Current	I <sub>FP</sub>	100	mA
Reverse voltage	V <sub>R</sub>	5	V
Electrostatic Discharge	ESD	2000	V
Operating temperature range	T <sub>op</sub>	-40~ +90	°C
Storage temperature range	T <sub>stg</sub>	-40 ~ +90	°C
Soldering Temperature	T <sub>slid</sub>	Reflow Soldering: 260° C	for 10sec.

1. IFP Conditions : 1/10 Duty Cycle, 0.1 msec Pulse Width
2. The device can not operated under continuous reverse voltage.

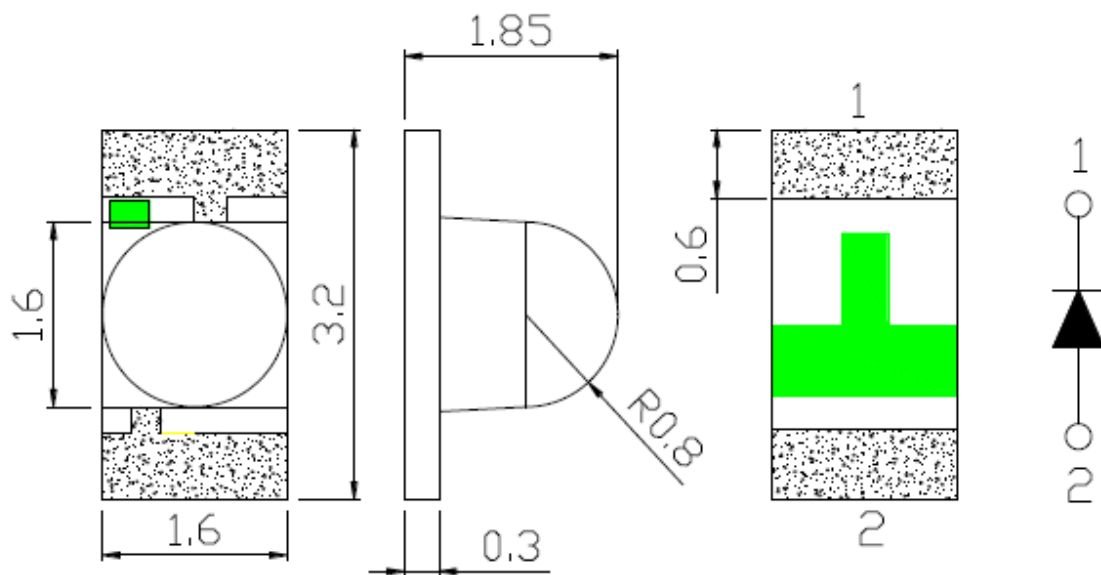
## ■ Electrical / Optical Characteristics –

(Ta=25°C)

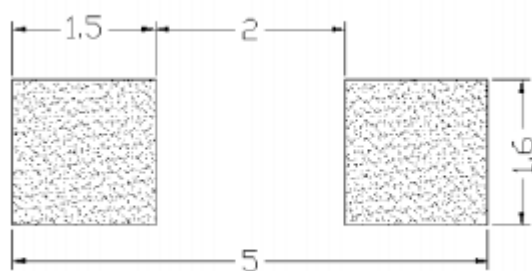
Parameter	Symbol	Value			Unit	Test Condition
		Min	Typ	Max		
Forward voltage	V <sub>f</sub>	2.9	3.0	3.4	V	I <sub>F</sub> =20mA
Luminous Intensity	I <sub>V</sub>	500	800	1000	mcd	
Dominant Wavelength	λ <sub>d</sub>	460	465	475	nm	
Peak Wavelength	λ <sub>p</sub>	--	470	--	nm	
Viewing angle at 50% I <sub>v</sub>	2 θ 1/2	--	30	--	Deg	
Reverse current	I <sub>r</sub>	--	--	10	μA	V <sub>R</sub> =10V

1. Luminous Intensity Measurement allowance is ± 10%.
2. Tolerance of measurement of V<sub>f</sub> is ±0.1 V..

■ Package Outline Dimensions –



■ Recommended Soldering Pattern –



**NOTES:**

All dimensions are in mm tolerance is  $\pm 0.2$  mm unless otherwise noted.

## ■ Bin Range of Luminous Intensity –

Bin Code	Min	Max	Condition
L1	500	1000	IF=20mA
L2	-	-	
L3	-	-	

Luminous Intensity Measurement allowance is  $\pm 10\%$ .

## ■ Bin Range Of Forward Voltage –

Bin Code	Min	Max	Condition
V1	2.9	3.0	IF=20mA
V2	3.0	3.1	
V3	3.1	3.2	
V4	3.2	3.3	
V5	3.3	3.4	

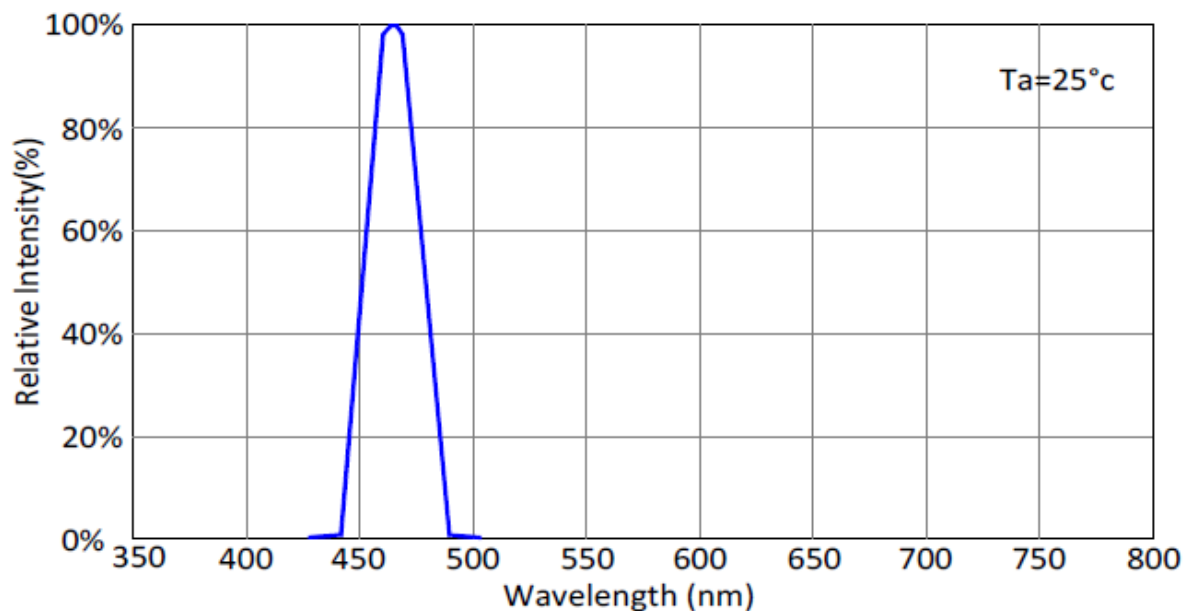
Tolerance of measurement of Vf is  $\pm 0.1V$ .

## ■ Bin Range Of Wavelength (Unit:nm)-

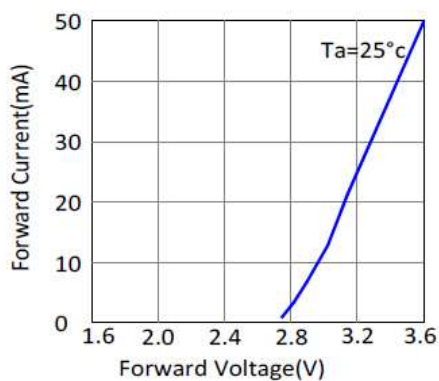
Bin Code	Min	Max	Condition
B1	460	462.5	IF=20mA
B2	462.5	465	
B3	465	467.5	
B4	467.5	470	
B5	470	472.5	
B6	472.5	475	

## Optical Characteristic Curves –

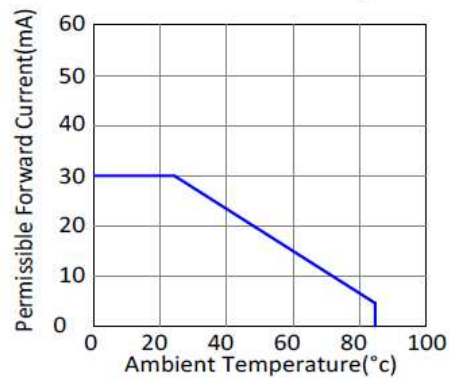
Spectral Power Distribution VS. Wavelength



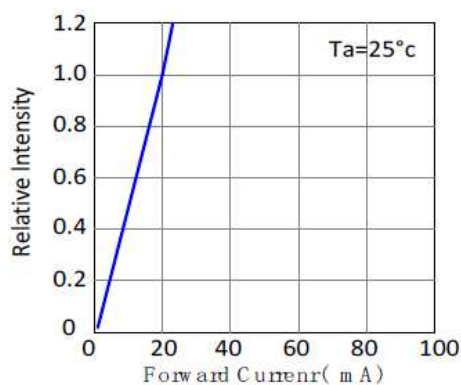
Forward Current vs. Forward Voltage



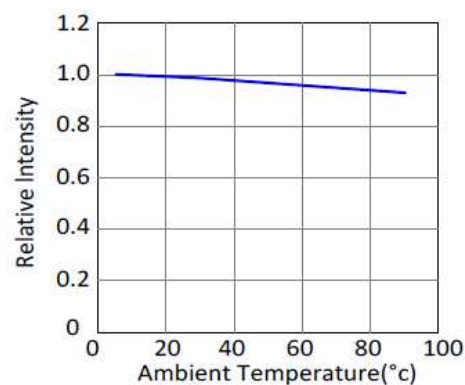
Forward Current vs. Ambient Temperature



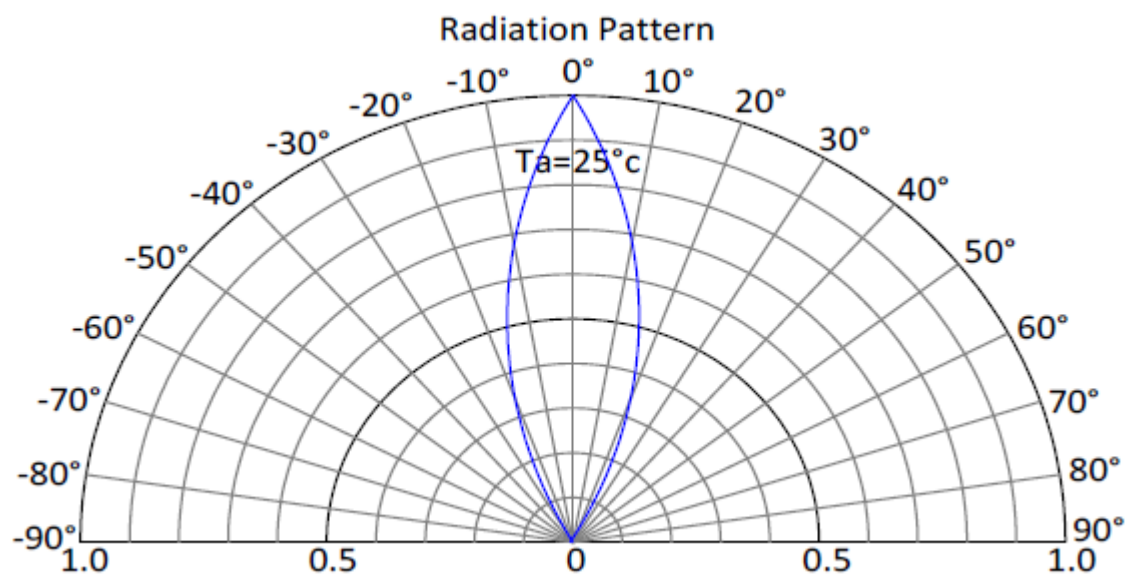
Relative Intensity vs. Forward Current



Relative Intensity vs. Ambient Temperature



Relative Luminosity VS. Radiation Angle

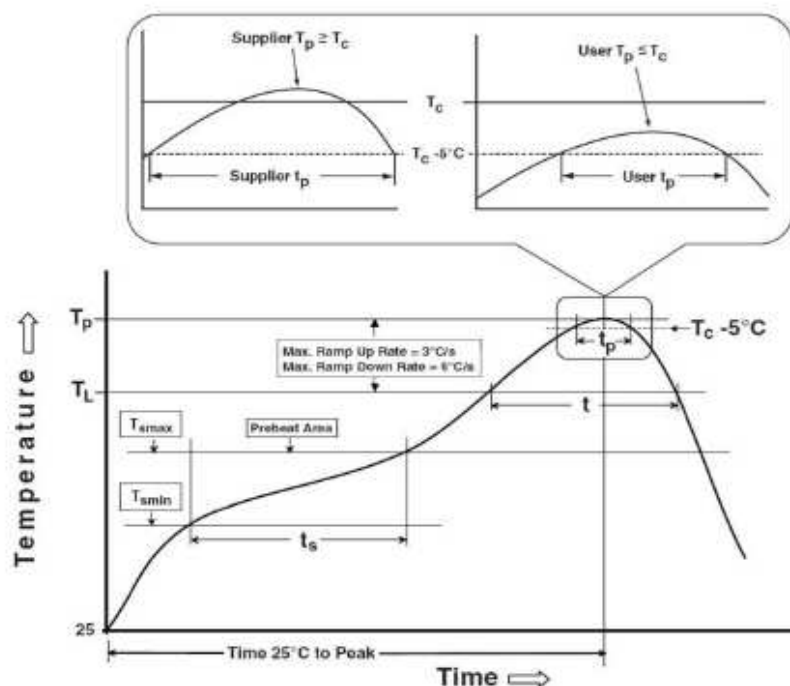


## ■ Cautions –

**Table of Classification Reflow Profiles**

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat & Soak	100 °C	150 °C
Temperature min (T <sub>smin</sub> )	150°C	200 °C
Temperature max (T <sub>smax</sub> )	60-120 seconds	60-120 seconds
Time (T <sub>smin</sub> to T <sub>smax</sub> ) (t <sub>s</sub> )		
Average ramp-up rate (T <sub>smax</sub> to T <sub>p</sub> )	3 °C/second max	3 °C/second max
Liquidous temperature (T <sub>L</sub> )	183 °C	217 °C
Time at liquidous (t <sub>L</sub> )	60-150 seconds	60-150 seconds
Peak package body temperature (T <sub>p</sub> )*	230 °C ~235 °C	255 °C ~260 °C
Classification temperature (T <sub>c</sub> )	235 °C	260 °C
Time (t <sub>p</sub> ) within 5 °C of the specified Classification temperature (T <sub>c</sub> )	20 seconds	30 seconds
Average ramp-down rate (T <sub>p</sub> to T <sub>smax</sub> )	6 °C/second max	6 °C/second max
Time 25 °C to peak temperature	6 minutes max	8 minutes max

1. Tolerance for peak profile temperature (T<sub>p</sub>) is defined as a supplier minimum and a user maximum.
2. Tolerance for time at peak profile temperature (t<sub>p</sub>) is defined as a supplier minimum and a user maximum.



## Precautions

### 1. Storage:

- Moisture proof and anti-electrostatic package with moisture absorbent material is used, to keep moisture to a minimum.
- Before opening the package, the product should be kept at 30℃ or less and humidity less than 60% RH, and be used within a year.
- After opening the package, the product should be stored at 30℃ or less and humidity less than 10%RH. It is recommended that the product be operated at the workshop condition of 30℃ or less and humidity less than 60%RH.
- If the moisture absorbent material has faded away or the LEDs have exceeded the storage time, baking treatment should be performed based on the following condition: (70±5)℃ for 24 hours.

### 2. Static Electricity:

Static electricity or surge voltage damages the LEDs. Damaged LEDs will show some unusual characteristics such as the forward voltage becoming lower, or the LEDs do not light at the low current, even not light.

All devices, equipment and machinery must be properly grounded. At the same time, it is recommended that wrist bands or anti-electrostatic gloves, anti-electrostatic containers be used when dealing with the LEDs.

### 3. Vulcanization:

LED curing is due to sulfur being in bracket and the +1 price of silver in the chemical reaction generated Ag<sub>2</sub>S in the process. It will lead to the capacity of reflecting of silver layer reducing, light color temperature drift and serious decline, seriously affecting the performance of the product. So we should take corresponding measures to avoid vulcanization, such as to avoid using sulphur volatile substances and keeping away from high sulphur content of the material.



## ■ Packaging –

The LEDs are packed in cardboard boxes after taping.

Taping Specifications (Units : mm)

Manner of packing

- Tape Specification: 3,000pcs Per Reel

